MARKET NEWS

Infineon expands DRIVECORE portfolio with three new software bundles, accelerating customer transition toward future RISC-V automotive microcontrollers

Munich, Germany – 3 March 2026 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) expands its DRIVECORE software portfolio with three new bundles designed to simplify and accelerate software-defined vehicle (SDV) development. At the center of this expansion is the new DRIVECORE bundle for the Infineon RISC-V Virtual Prototype, a key milestone in preparing the automotive ecosystem for Infineon's upcoming AURIX™ microcontroller (MCU) family based on RISC-V. With this latest step, Infineon continues to lead the transition toward open, scalable compute architectures and empowers customers and partners to begin software development for next-generation MCUs even before hardware becomes available.

Taking the next step toward RISC-V readiness

Infineon has committed to making RISC-V an open standard for the automotive industry. Following last year's introduction of its pre-silicon RISC-V virtual prototype at Embedded World 2025, Infineon now embeds this capability into the DRIVECORE portfolio to give automotive developers immediate access to a ready-to-use RISC-V evaluation environment. The new bundle integrates Infineon's AURIX™ RISC-V iLLDs, Synopsys Virtualizer Development Kit (VDK) for RISC-V, HighTec's automotive grade C/C++ compiler based on LLVM, as well as Lauterbach's TRACE32® Debug- and Trace-Solutions.

This fully pre-integrated environment allows customers and partners to evaluate the RISC-V architecture, begin pre-silicon software development in a shift-left approach, and validate toolchain readiness, significantly reducing development risk and accelerating time-to-market. The bundle is cloud-enabled, making evaluation even faster and easier.

"In the era of software-defined vehicles, rapid software migration, fast development cycles, and simple licensing is more important than ever," said Thomas Schneid, Head of Software, Partner and Ecosystem Management in Infineon's Automotive Division. "By adding our RISC-V Virtual Prototype to our DRIVECORE portfolio, we ease and prepare a smooth transition for our customers towards RISC-V-based microcontrollers."

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Expanding the DRIVECORE ecosystem across architectures
In addition to the RISC-V bundle, Infineon introduces two further DRIVECORE solutions targeting key automotive software domains.

The PSOC™ DRIVECORE Smart End Point bundle was developed together with Elektrobit and IAR and combines Infineon's proven PSOC™ hardware with Elektrobit's EB tresos AutoCore Light software and IAR's certified embedded toolchain. It provides a ready foundation for smart endpoint ECUs, supporting everything from first code build to functional safety evidence generation.

The AURIX DRIVECORE AUTOSAR bundle integrates Infineon MCAL drivers, Elektrobit's EB zoneo GatewayCore and EB tresos AutoCore stack, as well as TASKING SmartCode C/C++ Compiler Tool Chain. It is optimized for performance-efficient domain and zonal control ECUs and enables customers to accelerate AUTOSAR-based development while minimizing integration complexity.

Driving SDV innovation with a unified, scalable software foundation
All DRIVECORE bundles share the same principles: fully integrated, pre-tested software stacks paired with proven tooling and accompanied by a three-month free evaluation license. This allows immediate productivity, reduces migration effort, and eliminates supplier and license management complexity.

At launch, the combined ecosystem includes leading global and regional partners, ensuring customers have access to a diverse range of tools, middleware, libraries, and development expertise across RISC-V, Arm®, and TriCore™ architectures.

The three new bundles extend Infineon's mission to simplify automotive software development and support the global transition to software-defined vehicles across current and future microcontroller families.

Availability
The DRIVECORE RISC-V Virtual Prototype demo can be experienced at the booths of Lauterbach (Hall 4, Booth 4-210) and HighTec (Hall 4, Booth 4-432) at embedded world 2026. A PSOC™ DRIVECORE Smart End Point demo, featuring a rear lighting application will be showcased at the Infineon booth (Hall 4A, Booth 4A-138).

Further information is available at www.infineon.com/drivecore.

Infineon at embedded world
Embedded world will take place in Nuremberg, Germany, from 10 to 12 March, 2026. Infineon will present its products and solutions for decarbonization and digitalization in hall

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4A, booth 138. For press inquiries, please contact media.relations@infineon.com. Industry analysts interested in a briefing can email marketresearch.relations@infineon.com.

About Infineon

Infineon Technologies AG is a global semiconductor leader in power systems and IoT. Infineon drives decarbonization and digitalization with its products and solutions. The Company had around 57,000 employees worldwide (end of September 2025) and generated revenue of about €14.7 billion in the 2025 fiscal year (ending 30 September). Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the OTCQX International over-the-counter market (ticker symbol: IFNNY).

Further information is available at www.infineon.com
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